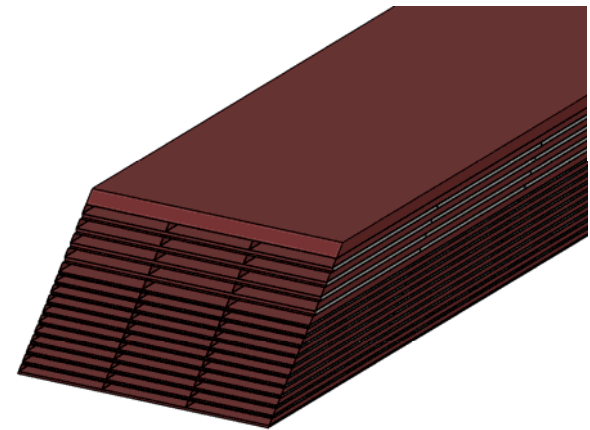


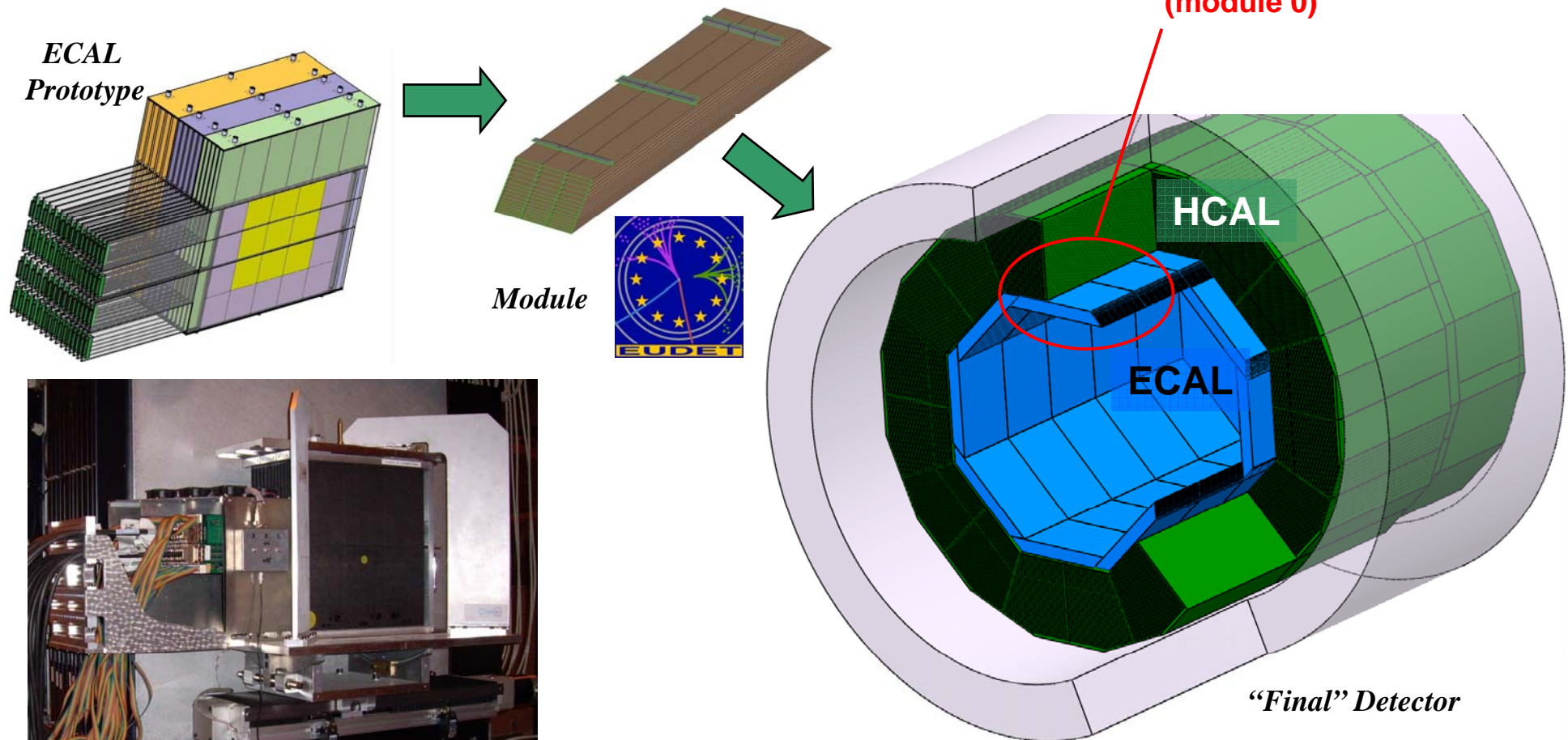
LM

Mechanical R&D for EUDET module



Why this prototype ?

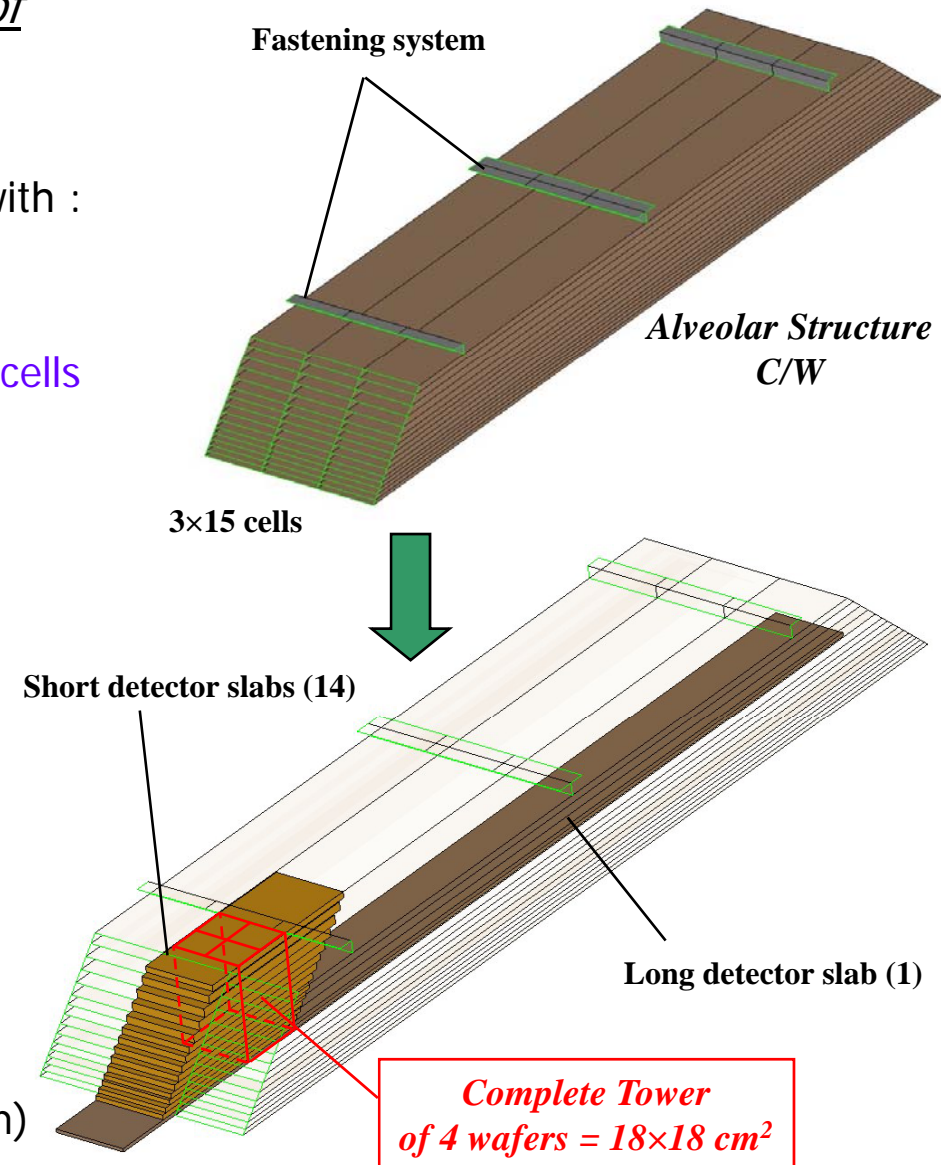
- ❑ Next step after the physics prototype and before the module 0
- ❑ To study “full scale” technological solutions which could be used for the final detector (moulding process, thermal cooling, inlet/outlet, integration tools ...)
- ❑ To take account of the industrial point of view
- ❑ To estimate the cost of the future Si/W ECAL



Global Presentation

Concept : to be the most representative of the final detector module :

- An alveolar composite/tungsten structure with :
 - same **W sampling** :
20×2.1 mm and 9×4.2 mm thick
 - 3 columns of cells to have **representative cells** in the middle of the structure (with thin composite sheets)
width : 124 mm → **182 mm**
 - Identical global dimensions (~1.5m long) and **shape** (trapezoidal)
 - **fastening system** ECAL/HCAL (include in the design of composite structure)
- 15 Detector slabs with **FE chips integrated**
 - **1 long** and **complete** slab ? (L=1.3m)
 - **14 short** slabs to obtain a complete **tower** of detection (typ. L=40 cm)
 - design of **compact outlet** (backend system)

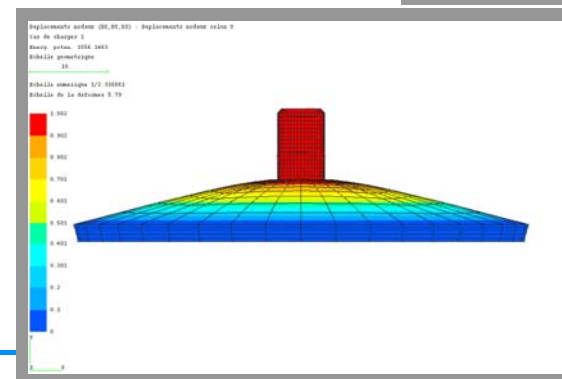
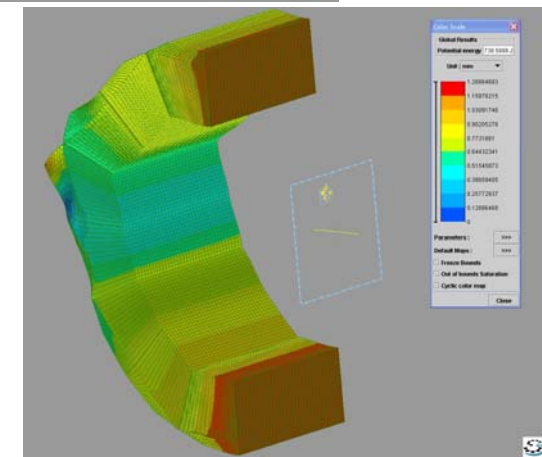
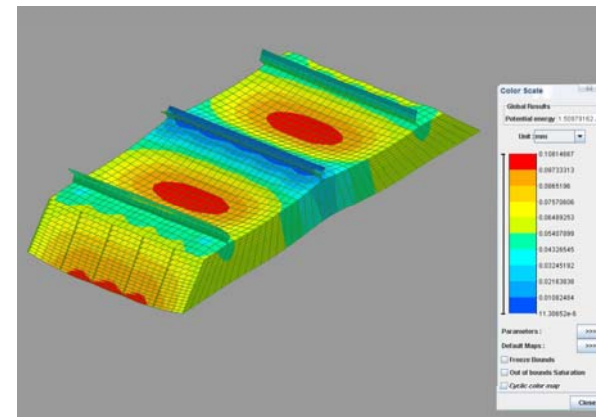


Design of the module...

... based on mechanical simulations :

Linear Analysis of "full scale" ECAL and HCAL modules

- Global simulations : global displacements and localization of high stress zone for different solutions (dimensions)
- Local simulations : more precise simulations and study of different local parameters to design correctly each part of this structure (**thickness** of main composite sheets, choice of **fasteners** : metal inserts, rails...)
- Check and validate simulation results by **destructive tests** for each issues



behaviour of
an insert in
composite with
tensile loads

Design of the module...

... while taking account of **Slab Thermal analysis**

Thermal sources:

Pad size	Chan/wafers	Ch/chip	Chip/wafer	Chip size mm ²	Chan/barrel	Chan/End-cap
5*5 mm ²	324	36	9	15x15	60.4 M	21.8 M

→ CALICE ECAL: ~ **82.2 M** of channels

total power to dissipate will be : ~ **2100 W**

⇒ external cooling OK for the "full scale ECAL"

inside each slab :

Assuming that the chip power is 25 μ W/channel
necessity of cooling system but **active** or **passive** ?

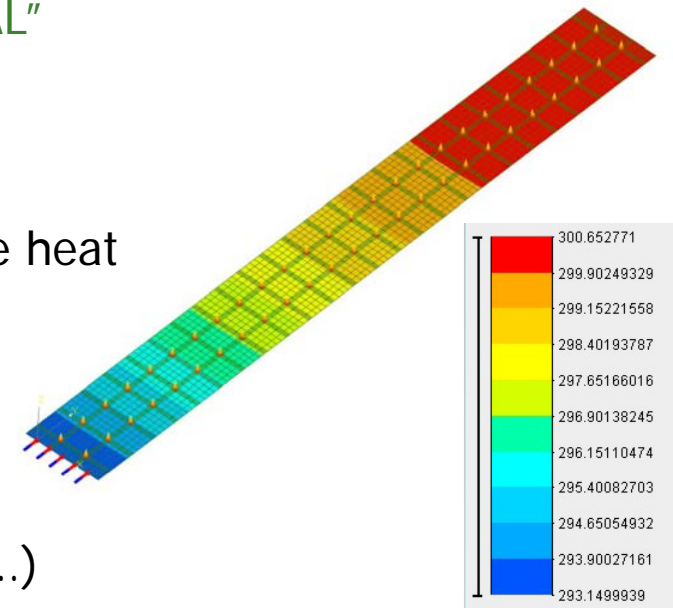
Ex: **Pessimist simulation** of heat conduction just by the heat

shield : $\lambda = 400$ W/m/K (copper) ; $S = 180 \times 0,4$ mm²
 $L = 1,55$ m ; $\Phi = 0,27$ W

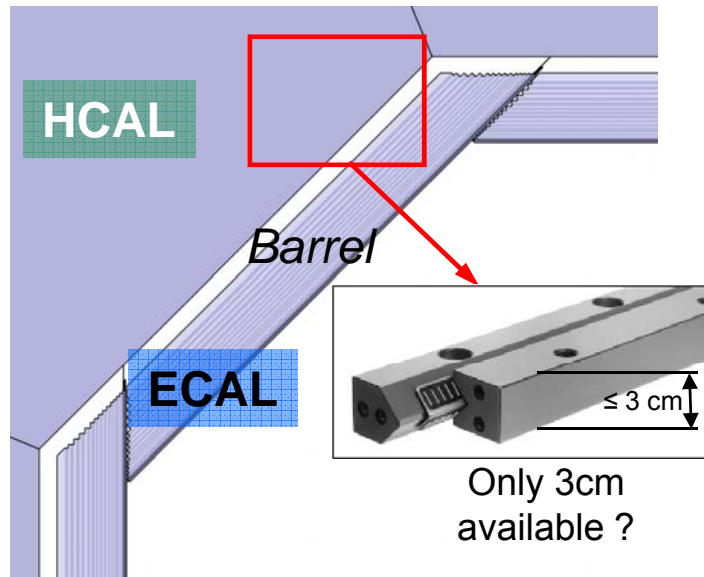
We can estimate the temperature difference along the slab layer around **8°C** and **without contribution** of all material from slab (PCB, tungsten, carbon fibers...)

⇒ **passive cooling OK** :

Thermal conductors (heat shield) can be added in the slab to carry heat more efficiently along the slab direction.



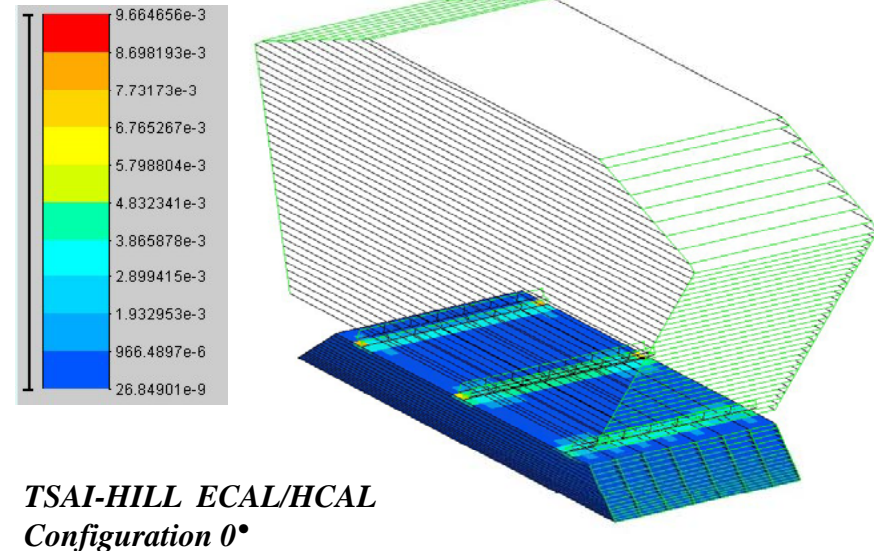
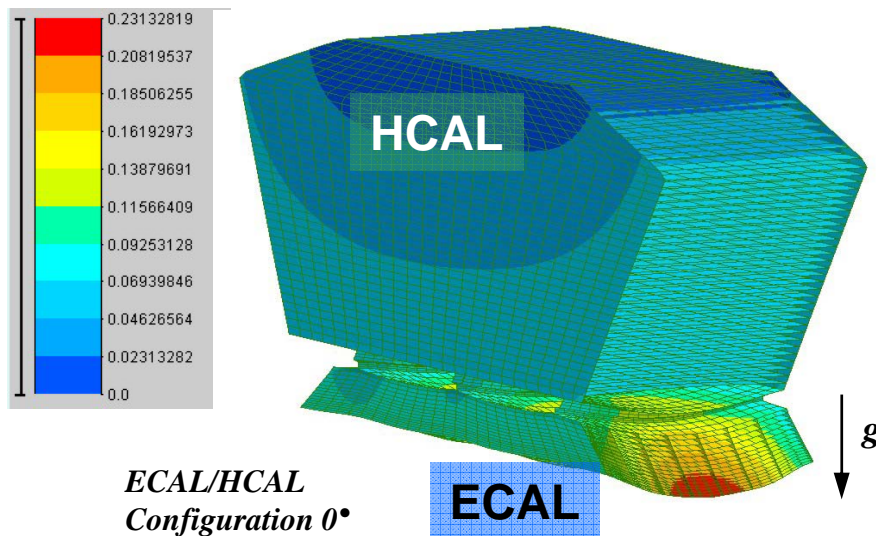
Design of the module...



... including ECAL/HCAL interfaces (+ inlet/outlet) :

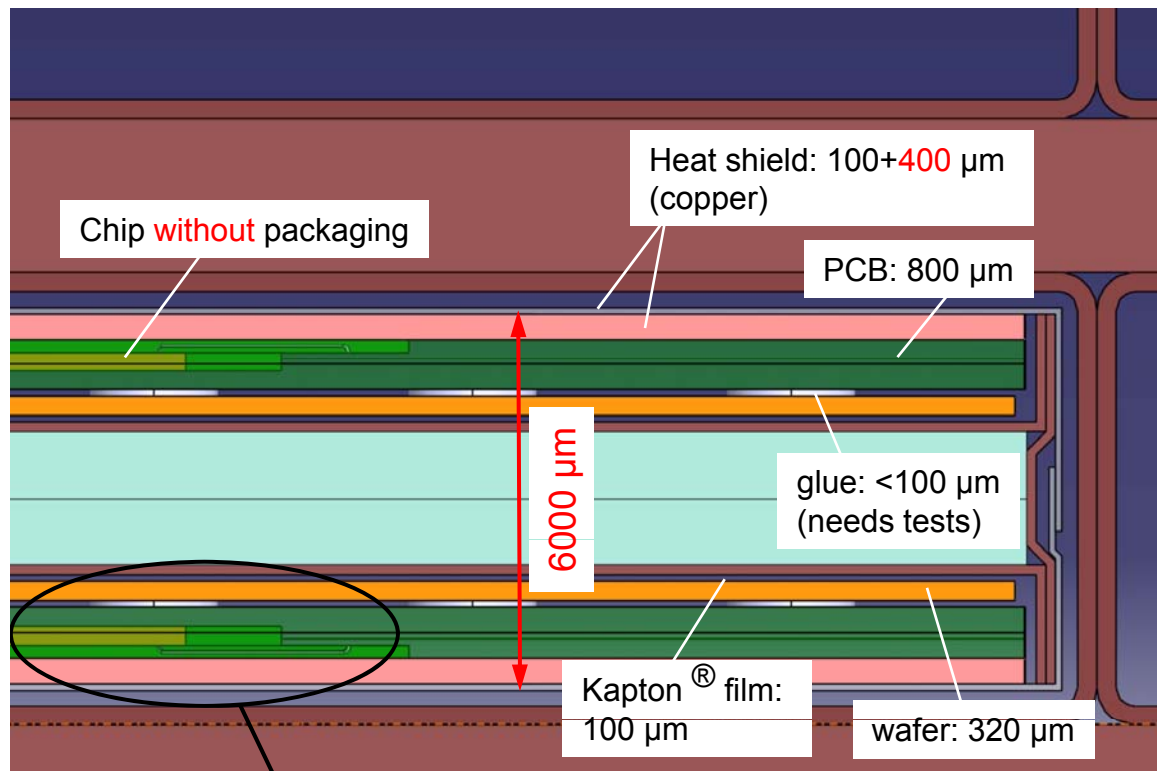
The fastening and connection system for the module has to be representative of the ECAL/HCAL interfaces.

- Choice of fasteners : rails directly glued on composite or metal inserts inside the structure ?
- Mechanical simulations of the ECAL/HCAL interface to take into account of its influence
- Design of connection system (power supply + cooling + outlets) : backend system ?



Design of the module...

... based on the definition of the detector slab :



Design EUDET Slab

Chips and bonded wires
inside the PCB

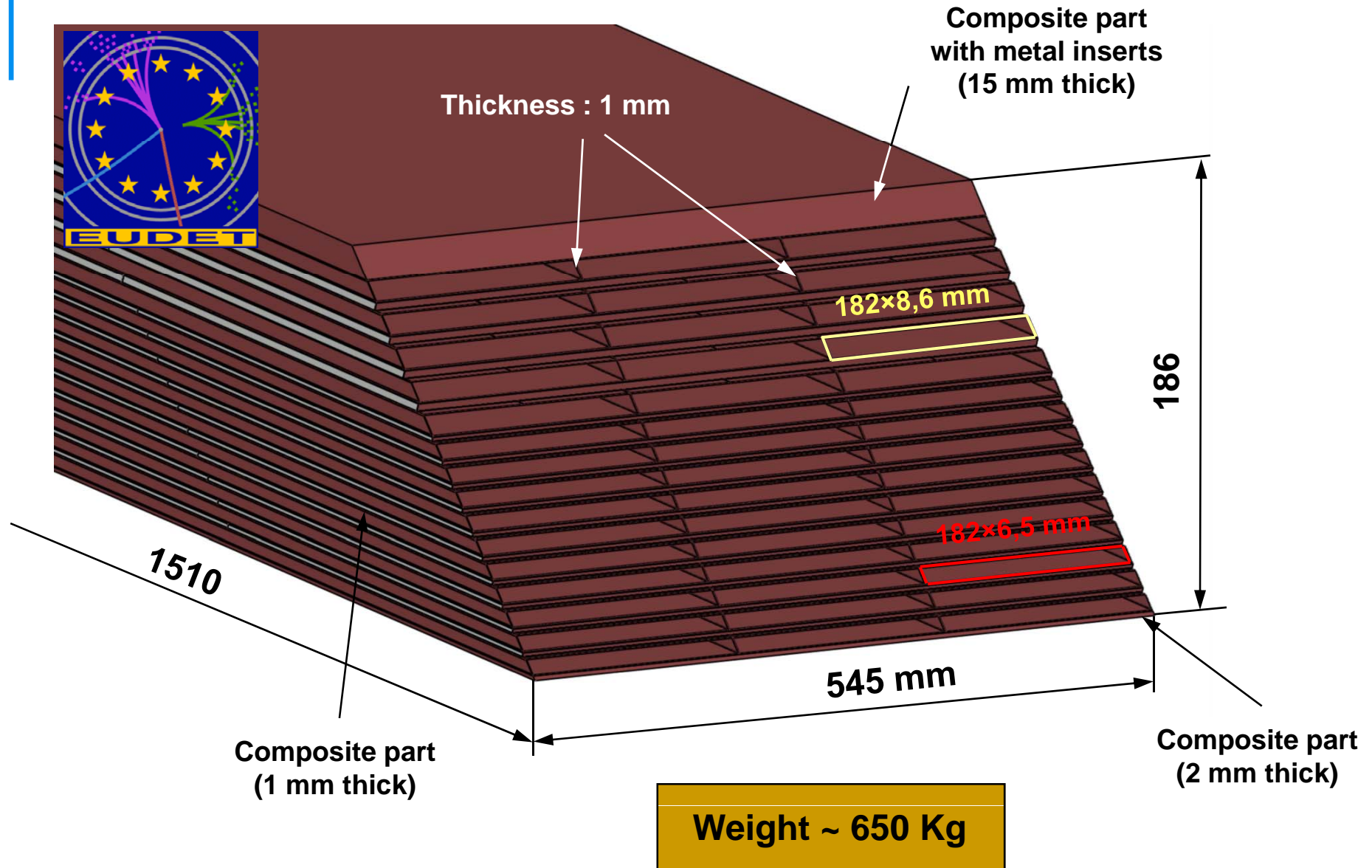


The expected alveolar thickness
is 6.5 mm **if** :

- ⇒ Gap (slab integration) : 500 μm ?
- ⇒ Heat shield : 400 μm ?
but real thermal dissipation ?
(active cooling ?)
- ⇒ PCB : 800 μm ?
but chips embedded in this thickness ?
- ⇒ Thickness of glue : <100 μm ?
study of the size of dots
- ⇒ Thickness of wafer : 320 μm - OK
30 matrices ordered (90×90 mm²)
- ⇒ Kapton[®] film for HV distribution :
100 μm - OK *(DC coupling)*
- ⇒ Thickness of W : 2100 μm - OK

*Several technological issues
have to be studied and validated*

The Design of alveolar structure



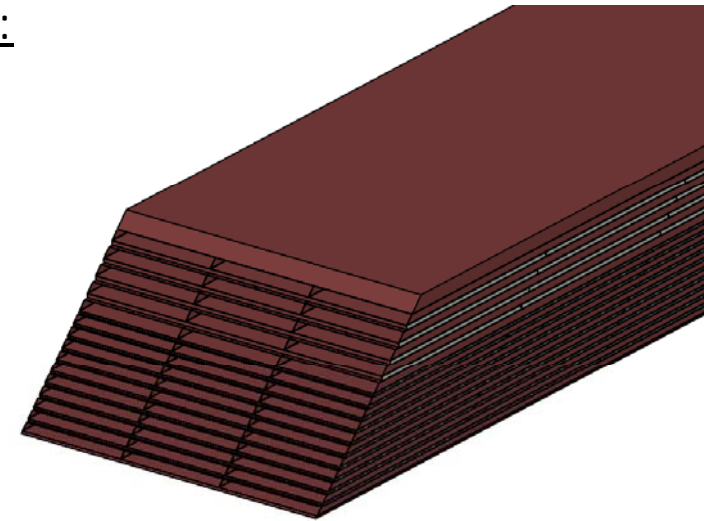
Composite Alveolar structure

Study of different principle (with industrial expertise):

■ Principle #1 : “one block” structure

One curing step to obtain the final structure

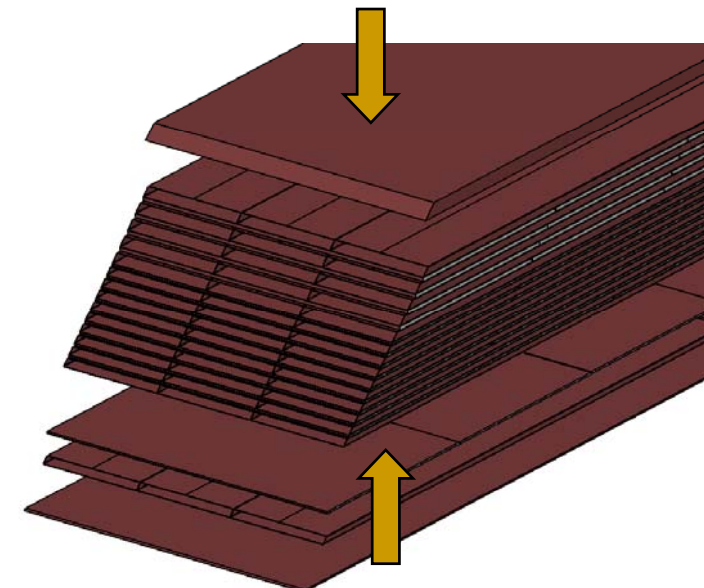
- Final piece in one step
- Better mechanical strength
- Only one but more complex mould (45 cores)
- Curing problems : thermal inertia, weigh of metal mould, control of curing parameters ...
- Important risks to fail the structure :
what about W plates ?



■ Principle #2 : Assembled structure

Each alveolar layer are done independently, cut to the right length (with 45°) and assembled with W plates in a second curing step

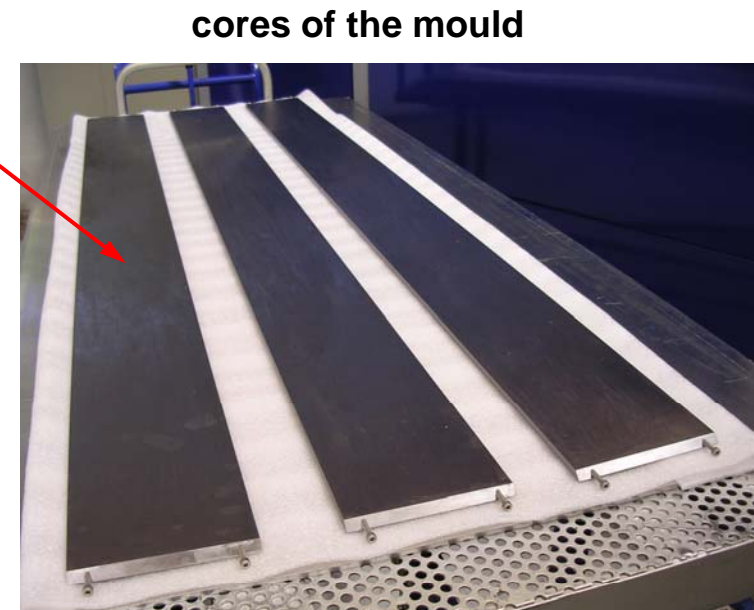
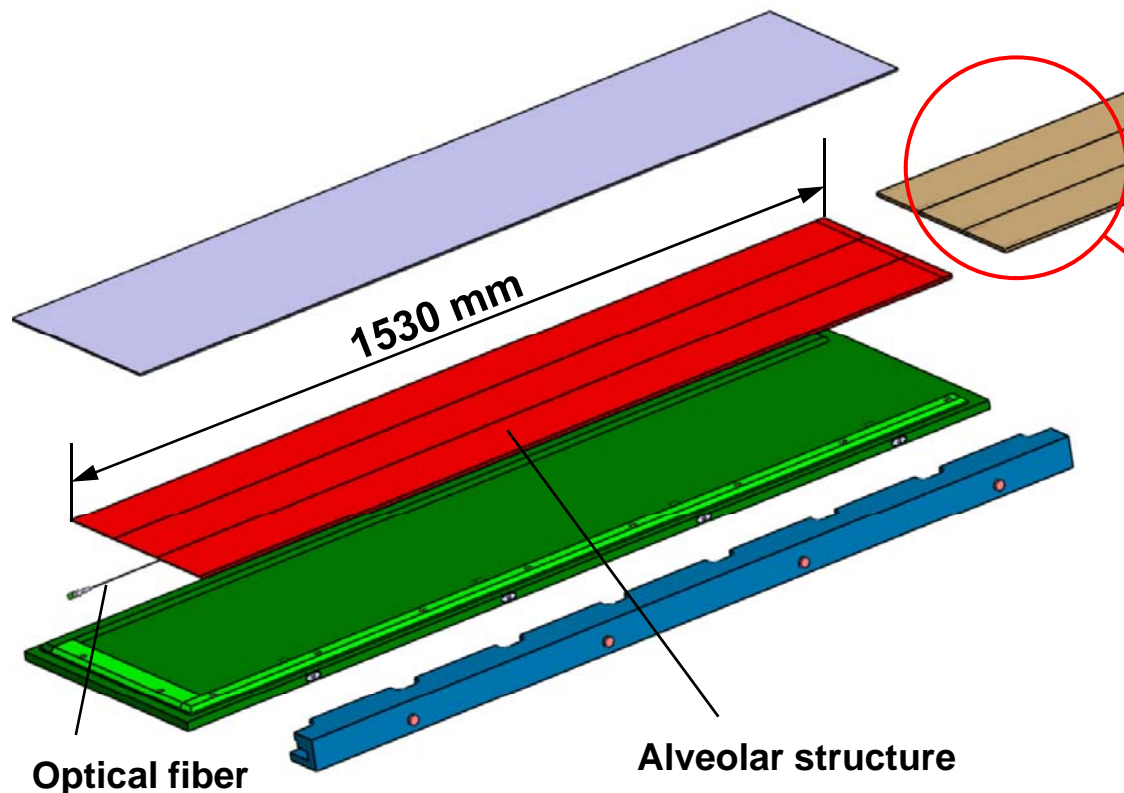
- Individual inspection and choice
- Limit risks to lose W plates
- Reduction of cost (simpler moulds)
- 2 polymerization process : 2 moulds
- Mechanical strength of “gluing” structures



« Alveolar layer » mould

Study of one first mould based on principle#2 :

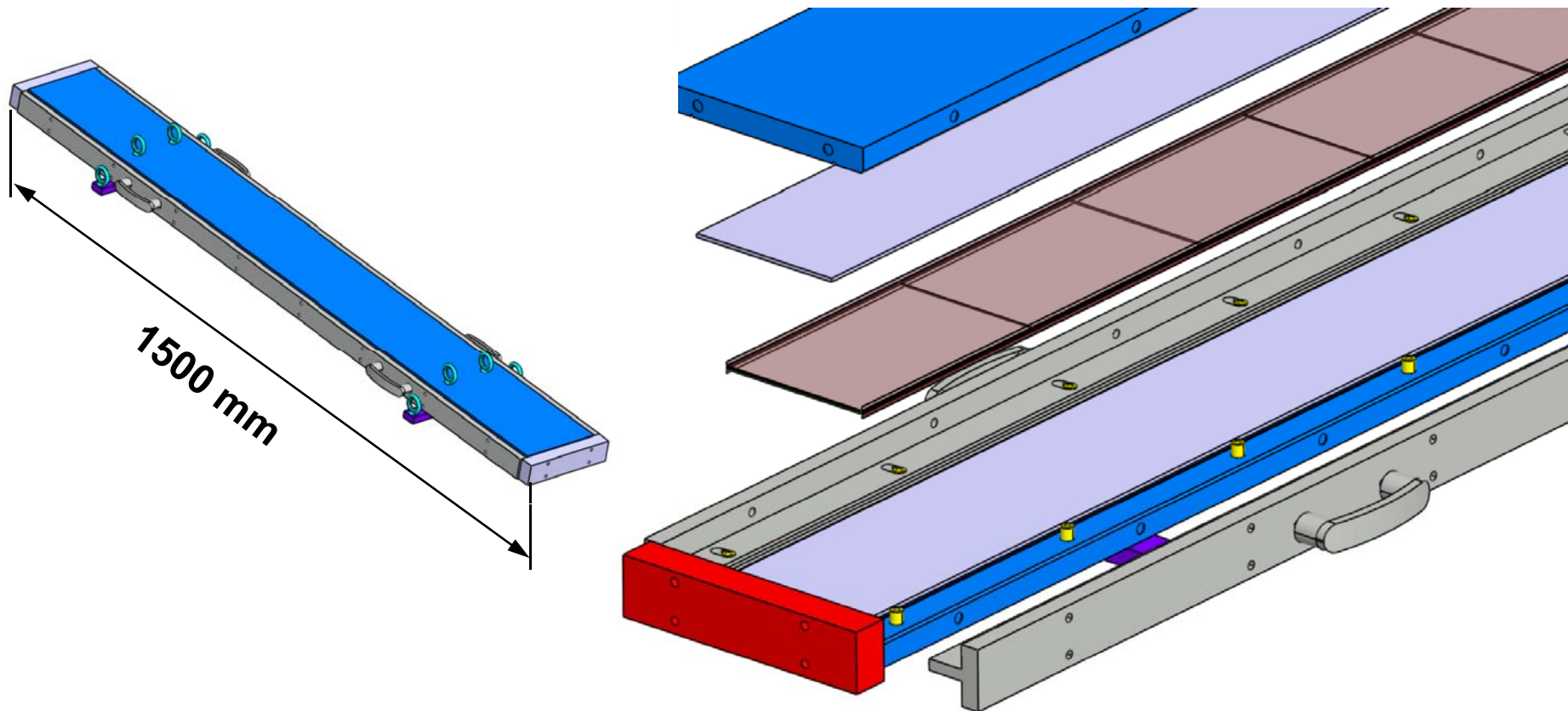
- Design of **one** mould for **all** alveolar layers
- Possibility to integrate **optical fiber with Bragg grating** for Tests-Simulations Dialogue
- The **length** of each layer will be obtained by machining one side (tools)
- First samples will use to **study mechanical behavior** (destroy tests, dimensional inspections ...)



Composite H structure

Study and definition of the long mould :

- Same principle than the mould used to do H prototype structures
- One mould for long and short structures

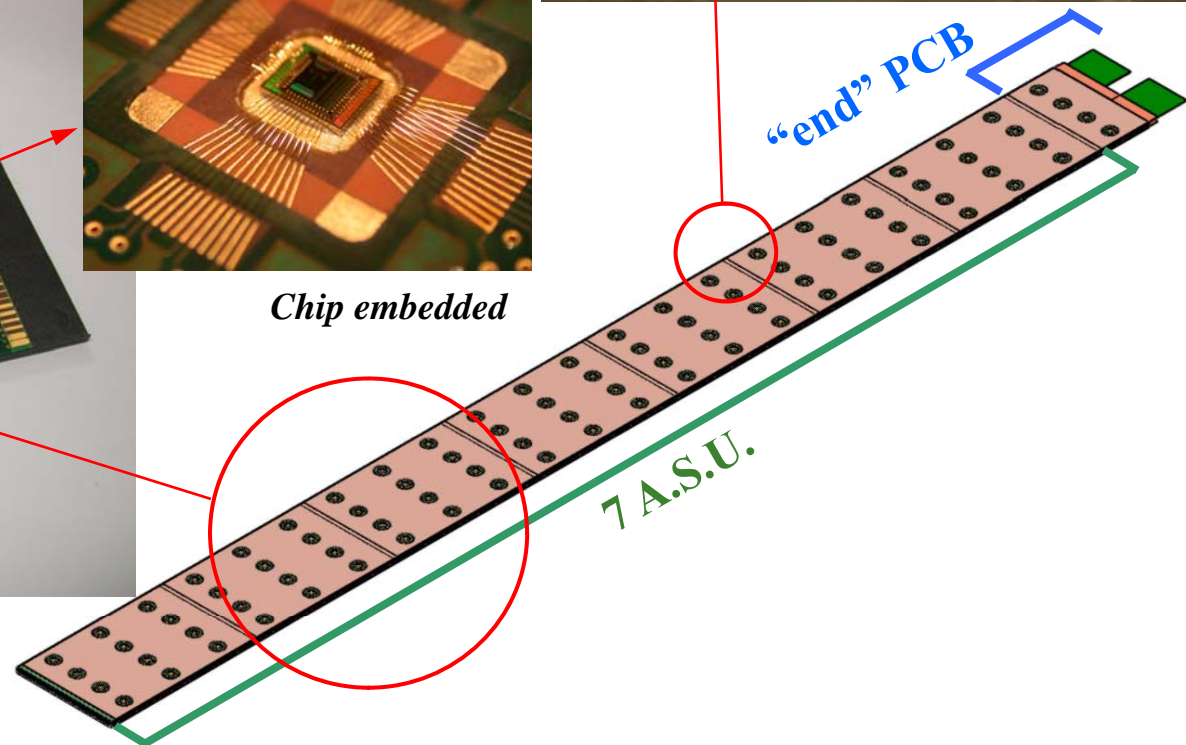
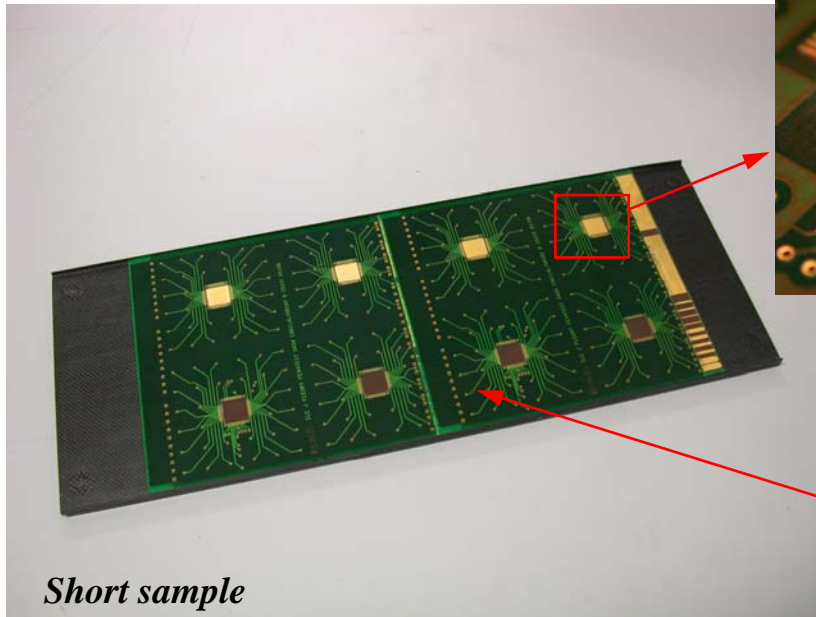
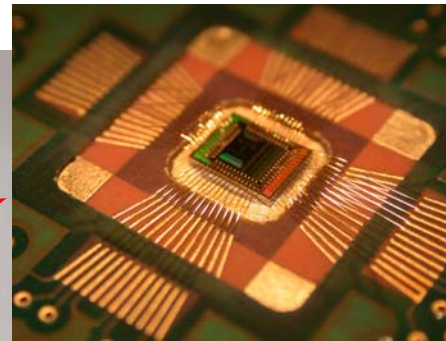
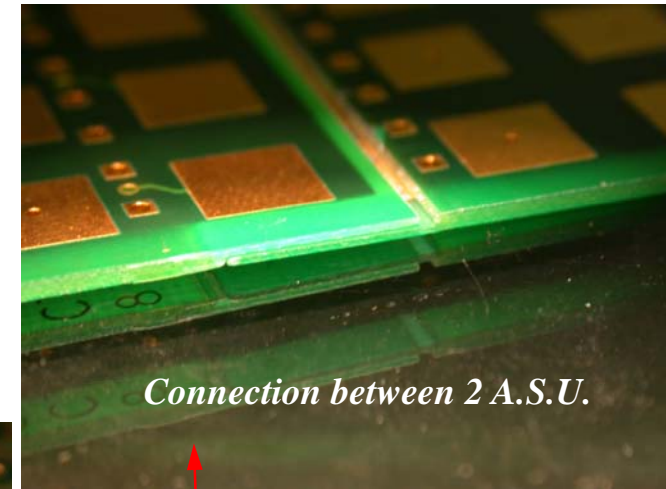


Detector slab - principle

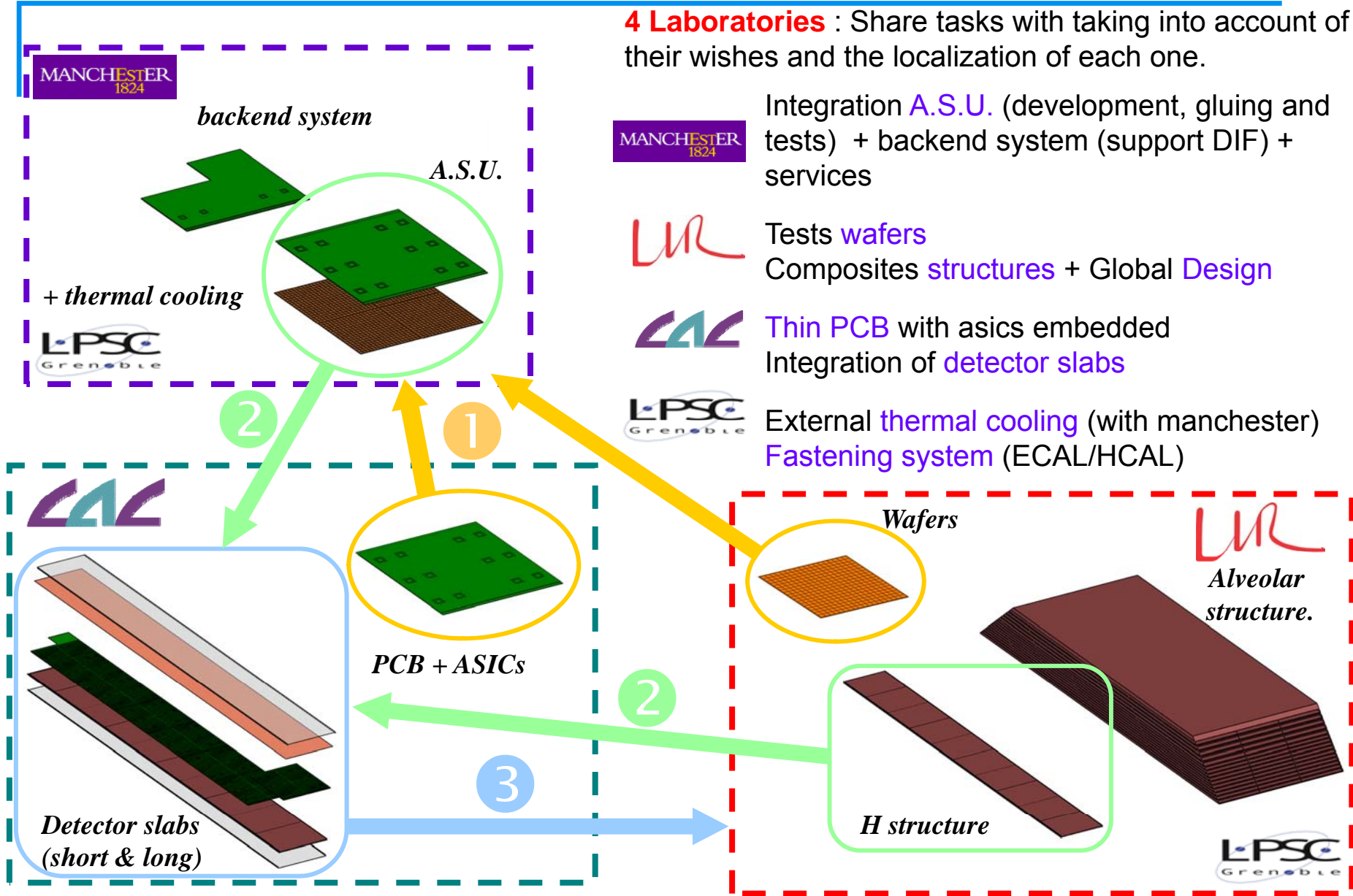
Long slab is made by several short PCBs :

A.S.U. : **A**ctive **S**ensors **U**nit

- ❑ Design of one **interconnection** (glue ?)
- ❑ Development easier : study, integration and tests of short PCB (with chips and wafers) **before assembly**
- ❑ The **length** of each long slab will be obtained by the size of one "end PCB" (tools)



Tasks distribution (proposal)



Conclusions

- **Global design** of the ECAL EUEDET module is well on going :
 - Main dimensions are fixed (checked by mechanical simulations)
 - W plates will be ordered soon, composite OK
 - First samples of wafers have been ordered

- Several **technological issues** are still under study and need to be validated (process for long composite structure, thin PCB with ASICs inside...)

- **4 laboratories** are interested on mechanical R&D :
One proposal to **share** responsibilities and **start main studies** in parallel :
A.S.U – Long SLAB – Composite Structures – Services

- **Dead line** for the ECAL EUEDET module construction : **mid 2009**